

Reliability and Test Condition

Item	Performance	Test Condition
<b>Solderability</b>	More than 95% of the terminal shall be covered with fresh solder	Preheat : 125 ± 25°C for 60sec Solder : 99%Sn/0.3%Ag/0.7%Cu or Equivalent Solder Temperature : 245 ± 5°C Dip Time : 4 ±1sec
<b>Terminal Strength (Leaded)</b>	Appearance : Cracking , chipping and any other defects harmful to the characteristics should not be allowed.	Pull Test Applied force: 1.45kg-mm Duration : 5 to 10 sec
<b>Thermal Shock</b>		Step1 : -40 ± 2°C 30min Min Step2 : Transition time 1min MAX Step3 : 125 ± 2°C 30min Min.  Step4 : Transition time 1min MAX Number of cycles : 50 Measured at room temperature after placing for 24 ± 2 hrs
<b>Humidity Resistance Test</b>	Appearance : Cracking , chipping and any other defects harmful to the characteristics should not be allowed.  Inductance : Within ±10% of initial value. Hi-Pot : Shall compliance to test requirement stated.	Humidity : 90 ~ 95 % R.H, Temperature : 60°C ± 2°C Duration : 500hrs Min. with 100% rated current  Measured at room temperature after placing for 24 ± 2 hrs
<b>Vibration Test</b>		Reference standard :  MIL-STD -202 METHOD 204 Oscillation Frequency: 10~2kHz~10Hz for 20 minutes Equipment : Vibration checker Total Amplitude:1.52mm ±10%  Testing Time : 12 hrs(20 minutes, 12 cycles each of 3 orientations)

